Authorized Representative* Title - Representative Phone - Representative* Email - Representative*	assembly with lower responsibility.		
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-15 Contact Name Title - Contact Product Enviro Compliance NA Product Envistewards Product Enviro Compliance NA Product Enviro Compliance NA Product Envistewards @onsemia Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3			
nsemi ontact Name Title - Contact Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Product-En			
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Product-Env-Stewards Uthorized Representative* Title - Representative Product-Env-Stewards Pr	2024-05-15		
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Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM MIL21193G BIP T0264 PNP 16A 250V 2024-05-15 KR8 10737.244 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy NA Product-Env-Stewards@onsemi. Weight* UOM Product-Env-Stewards@onsemi. Manufacturing Site Weight* UOM Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Compliance NA O C 30 Seconds 3	Product-Env-Stewards@onsemi.com		
Requester Item Number	Email - Representative*		
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Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Companies of Matter Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Each		
Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	,		
Figure 1 in (bit) dimension of the property of	cles		
milients			
or more information regarding material composition please refer to page 3			

RoHS Material Composition Declaration			Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for C n (Cr6+), Polybrominated Biphenyls (PBB), Polybro Diisobutyl phthalate (DIBP).						
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.								
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).								
Exemption List Version	EL-2011/534/EU							
Declaration Signature								
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature Ra	astislav Drska	-En						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.004	mg	Supplier	Silicon (Si)	7440-21-3		0.004	mg
Die Attach	438.49	mg	A	Lead (Pb)	7439-92-1	7a	416.5655	mg
			Supplier	Tin (Sn)	7440-31-5		21.9245	mg
Lead Frame	6869.64	mg	Supplier	Zinc (Zn)	7440-66-6		6.8696	mg
			Supplier	Iron (Fe)	7439-89-6		6.8696	mg
			Supplier	Copper (Cu)	7440-50-8		6855.9009	mg
Mold Compound-Black	3393.27	mg		Brominated epoxy resin	proprietary data		135.7308	mg
			Supplier	Phenolic Resin	Proprietary Data		173.0568	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		44.1125	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2694.2566	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		346.1133	mg
Plating	34.3	mg	Supplier	Tin (Sn)	7440-31-5		34.3	mg
Wire Bond - Al	1.54	mg	Supplier	Aluminum (Al)	7429-90-5		1.54	mg